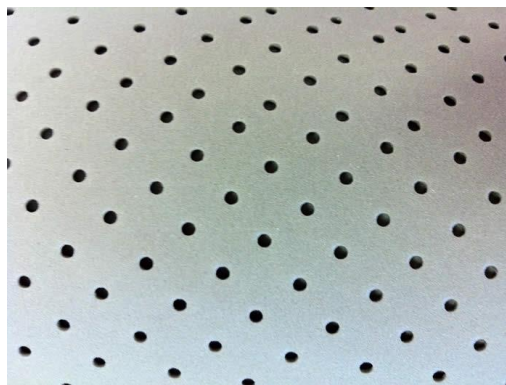




LIGNUM ADDITIONS

Lignum Design Quicktransfer

The perforated structure of the Quicktransfer underlay is unique and facilitates the transmission of heat. With Quicktransfer underlay you are sure to reach top efficiency of your flooring heating system. This low tog (0.35 Togs) underlay is designed for underfloor heating. Thermal resistance is $RB=0.035m^2K/W$ which means that the tog rating will be 0.35 togs. It is recommended that the heat transmission resistance of flooring and underlay must not exceed a value of $RB= 0.15 m^2K/W$. This means that the thinner the engineered or laminate floor the better the transfer of heat.



Technical Specification

- Quicktransfer underlay ensures sound reduction of your flooring. Impact and Drum sound are reduced.
- Density of the EVA foam in the Quicktransfer underlay is 30kg/m³.
- Ideal for rooms with heavy traffic.
- We recommend using in conjunction with a Vapour Barrier for high moisture sub-floor

The information given above may vary and is partly based on information from our suppliers. It represents the prevailing level of expertise and is not binding in a legal sense. The compliance of legal requirements lies within the customers own responsibility.